

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	251240	(flexible bent bentable bending bented) with (layer substrate carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/16 18:33
L2	41515	(die chip ic electronic (integrated adj circuit) semiconductor) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/16 18:35
L3	8960	(resilient metal stiff stiffen stiffening resiliently) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/16 18:37
L4	2498	3 same (trace wiring wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/16 18:38
L5	971	4 and (package packaged packaging)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/16 18:38